UNITED STATES PATENT AND TRADEMARK OFFICE **CERTIFICATE OF CORRECTION**

PATENT NO.

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Page 1 of 1

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INVENTOR(S)

: August 22, 2006 : Hong Wan et al.

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the title page, at item [57], please delete: "Methods and apparatus for vertical chip-on-board sensor packages..." and replace with -- Methods and apparatus for vertical die chip-on-board sensor packages.... --

In claim 11, Column 14, line 14, please delete "alone" and substitute -- along --.

Signed and Sealed this

Eighteenth Day of September, 2007

JON W. DUDAS Director of the United States Patent and Trademark Office